12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20160323001
HD3SS3412RUAR/T Die Revision Change
Change Notification / Sample Request

Date: 3/23/2016
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20160323001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
HD3SS3412RUAT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160323001	**PCN Date:**	03/23/2016
Title:	HD3SS3412RUAR/T Die Revision Change		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	06/23/2016	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☒	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This notification is to inform of a die revision change to select devices. Design changes were made to improve the power performance in the device. The power improvements are achieved through design optimization of bias circuits, charge pump and adaptive common mode voltage regulator. There is no change to the device functionality. The high speed switch network remained unchanged. The design changes do not affect the device's guaranteed datasheet specifications or electrical performance.

Affected devices are listed in the product affected section of this document.

Reason for Change:

Improved product performance

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in the table and sample label below:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
B	-

Sample product shipping label (not actual product label)

Product Affected:

HD3SS3412RUAR	HD3SS3412RUAT

Qualification Report

HD3SS3412RUA Die Rev D
Approve Date 16-Mar-2016

Product Attributes

Attributes	Qual Device: HD3SS3412RUA _REV1	Qual Device: HD3SS3412RUA _REV0	QBS Process Reference: HD3SS3411TRWA Q1	QBS Package Reference: AMC7823IRTA.	QBS Package Reference: SH6966ACC0RGCR G4 _CU_WIRE
Assembly Site	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT
Package Family	QFN	QFN	QFN	QFN	QFN
Wafer Fab Supplier	FFAB	FFAB	FFAB	TSMC FAB2B	MIHO8
Wafer Fab Process	1833BICOM3ZL_RF	1833BICOM3ZL_RF	1833BICOM3ZL_RF	0.6 DPTM	LBC7

- QBS: Qual by Similarity
- Qual Device HD3SS3412RUA_REV0 is qualified at LEVEL3-260C
- Qual Device HD3SS3412RUA _REV1 is qualified at LEVEL3-260C
- Device HD3SS3412RUA_REV0 contains multiple dies.
- Device HD3SS3412RUA _REV1 contains multiple dies.

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: HD3SS3412 RUA _REV1	Qual Device: HD3SS3412 RUA _REV0	QBS Process Reference: HD3SS3411TRWA Q1	QBS Package Reference: AMC7823IRTA.	QBS Package Reference: SH6966ACC0RGCR G4 _CU_WIRE
AC	Autoclave 121C	96 Hours	-	-	3/231/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	-	-
ELFR	Early Life Failure Rate, 140C	24 Hours	-	-	3/2400/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	3/231/0
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	2/90/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	-	-	-	-
SD	Surface Mount Solderability	Pb Free	-	-	1/15/0	3/66/0	-
SD	Surface Mount Solderability	Pb Solder	-	-	1/15/0	3/66/0	-
TC	Temperature Cycle -65/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0	3/231/0
TS	Thermal Shock - 65/150C	500 Cycles	-	-	-	3/231/0	3/231/0
WBP	Bond Pull	Wires	1/76/0	-	-	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	-	-	3/228/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com